

## ABSTRACT

The present invention discloses a substrate clamp and a substrate treatment apparatus. The substrate clamp comprises: a plurality of support members, mounted on a fixing ring and sequentially arranged along the circumferential direction of an opening; each support member including a connecting portion and a contact which are conductively connected, the surface of the connecting portion being provided with an insulating layer, and the contact being used for electrically contacting with a substrate. Wherein, the contact is connected to the fixing ring at a preset distance through the connecting portion, so that during the substrate treatment, the fixing ring is above the liquid level of a treatment solution while the contact and the substrate carried on the contact are below the liquid level. The present invention achieves the effect of reducing electrical contact between the substrate clamp and the treatment solution during the substrate treatment.